

What is claimed is:

(Claim 1) 1. A package structure that is compatible with a cooling system, comprising:

a carrier;

at least a chip, arranged on the carrier and electrically connected to the carrier;

a mold compound, covering the chip and one surface of the carrier; and

a cooling tubule, attached to an outer surface of the mold compound via an adhesive, wherein the cooling tubule is connected to the cooling system, wherein the cooling system is a closed system and a fluid driven by a pump circulates within the cooling tubule and the cooling system.

(Claim 2) 2. The package structure of claim 1, wherein the cooling system comprises a cooling tubing and the cooling tubule is connected to the cooling tubing.

(Claim 3) 3. The package structure of claim 1, wherein the fluid is selected from the group consisting of water, a coolant and a gas.

(Claim 4) 4. The package structure of claim 1, wherein the cooling system further comprises a cooler connected to the cooling tubing.

(Claim 5) 5. The package structure of claim 1, wherein a material of the mold compound includes thermosetting plastics.

(Claim 6) 6. The package structure of claim 1, wherein a material of the mold compound includes an epoxy resin.

(Claim 7) 7. The package structure of claim 1, wherein a material of the adhesive includes a thermally conductive adhesive.

(Claim 8) 8. The package structure of claim 7, wherein the adhesive covers a portion of the outer surface of the mold compound.